

- **Qualification in Accordance With AEC-Q100†**
- **Qualified for Automotive Applications**
- **Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval**
- **Member of Texas Instruments Widebus™ Family**
- **Standard '16245-Type Pinout**
- **5-Ω Switch Connection Between Two Ports**
- **TTL-Compatible Input Levels**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection Exceeds JESD 22**
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

† Contact factory for details. Q100 qualification data available on request.

## description/ordering information

The SN74CBT16245 device provides 16 bits of high-speed TTL-compatible bus switching in a standard '16245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as two 8-bit low-impedance switches with separate output-enable ( $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the switch is on, and data can flow from the A port to the B port, or vice versa. When  $\overline{OE}$  is high, the switch is open, and the high-impedance state exists between the two ports.

## DGG OR DL PACKAGE (TOP VIEW)

NC	1	48	$\overline{1OE}$
1B1	2	47	1A1
1B2	3	46	1A2
GND	4	45	GND
1B3	5	44	1A3
1B4	6	43	1A4
V <sub>CC</sub>	7	42	V <sub>CC</sub>
1B5	8	41	1A5
1B6	9	40	1A6
GND	10	39	GND
1B7	11	38	1A7
1B8	12	37	1A8
2B1	13	36	2A1
2B2	14	35	2A2
GND	15	34	GND
2B3	16	33	2A3
2B4	17	32	2A4
V <sub>CC</sub>	18	31	V <sub>CC</sub>
2B5	19	30	2A5
2B6	20	29	2A6
GND	21	28	GND
2B7	22	27	2A7
2B8	23	26	2A8
NC	24	25	$\overline{2OE}$

NC – No internal connection

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP – DL	Tape and reel	SN74CBT16245IDLRQ1§	CBT16245I
	TSSOP – DGG	Tape and reel	CCBT16245IDGGRQ1	CBT16245I

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

§ Product Preview

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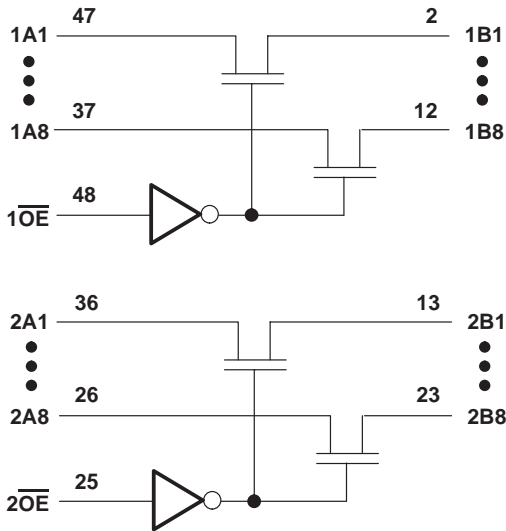
SN74CBT16245-Q1  
16-BIT FET BUS SWITCH

SCDS170 – JULY 2004

FUNCTION TABLE  
(each 8-bit bus switch)

INPUT OE	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, $I_{IK}$ ( $V_{I/O} < 0$ )	–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DGG package	70°C/W
DL package	63°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
$V_{CC}$ Supply voltage	4	5.5	V
$V_{IH}$ High-level control input voltage	2		V
$V_{IL}$ Low-level control input voltage		0.8	V
$T_A$ Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN74CBT16245-Q1 16-BIT FET BUS SWITCH

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$V_{IK}$		$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$			-1.2	V
$I_I$		$V_{CC} = 0$ , $V_I = 5.5\text{ V}$			10	$\mu\text{A}$
		$V_{CC} = 5.5\text{ V}$ , $V_I = 5.5\text{ V}$ or GND			$\pm 1$	
$I_{CC}$		$V_{CC} = 5.5\text{ V}$ , $I_O = 0$ , $V_I = V_{CC}$ or GND			3	$\mu\text{A}$
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5\text{ V}$ , One input at 3.4 V, Other inputs at $V_{CC}$ or GND			2.5	$\text{mA}$
$C_i$	Control inputs	$V_I = 3\text{ V}$ or 0			3.5	$\text{pF}$
$C_{io}(\text{OFF})$		$V_O = 3\text{ V}$ or 0, $\overline{OE} = V_{CC}$			4.5	$\text{pF}$
$r_{on}^\S$		$V_{CC} = 4\text{ V}$ , TYP at $V_{CC} = 4\text{ V}$ , $V_I = 2.4\text{ V}$ , $I_I = 15\text{ mA}$		14	20	$\Omega$
		$V_{CC} = 4.5\text{ V}$ , $V_I = 0$ , $I_I = 64\text{ mA}$		5	7	
		$V_{CC} = 4.5\text{ V}$ , $V_I = 0$ , $I_I = 30\text{ mA}$		5	7	
		$V_{CC} = 4.5\text{ V}$ , $V_I = 2.4\text{ V}$ , $I_I = 15\text{ mA}$		8	12	

† All typical values are at  $V_{CC} = 5\text{ V}$  (unless otherwise noted),  $T_A = 25^\circ\text{C}$ .

‡ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

**switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\P$	A or B	B or A		0.35		0.25	ns
$t_{en}$	$\overline{OE}$	A or B		6.1	1.2	5.6	ns
$t_{dis}$	$\overline{OE}$	A or B		7.5	3.9	7.7	ns

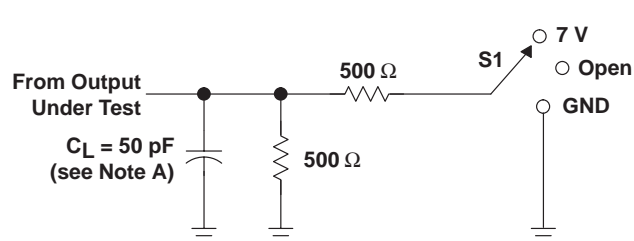
¶ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

# SN74CBT16245-Q1

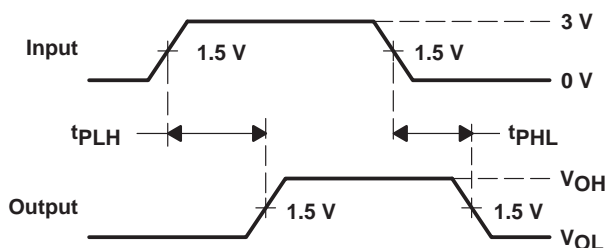
## 16-BIT FET BUS SWITCH

SCDS170 – JULY 2004

### PARAMETER MEASUREMENT INFORMATION

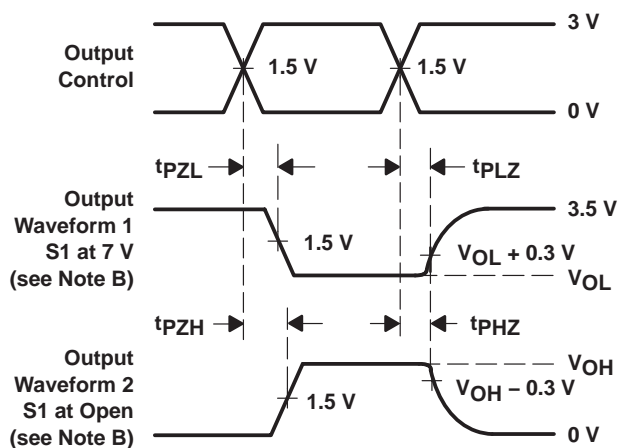


LOAD CIRCUIT



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES

TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CCBT16245IDGGRQ1	ACTIVE	TSSOP	DGG	48	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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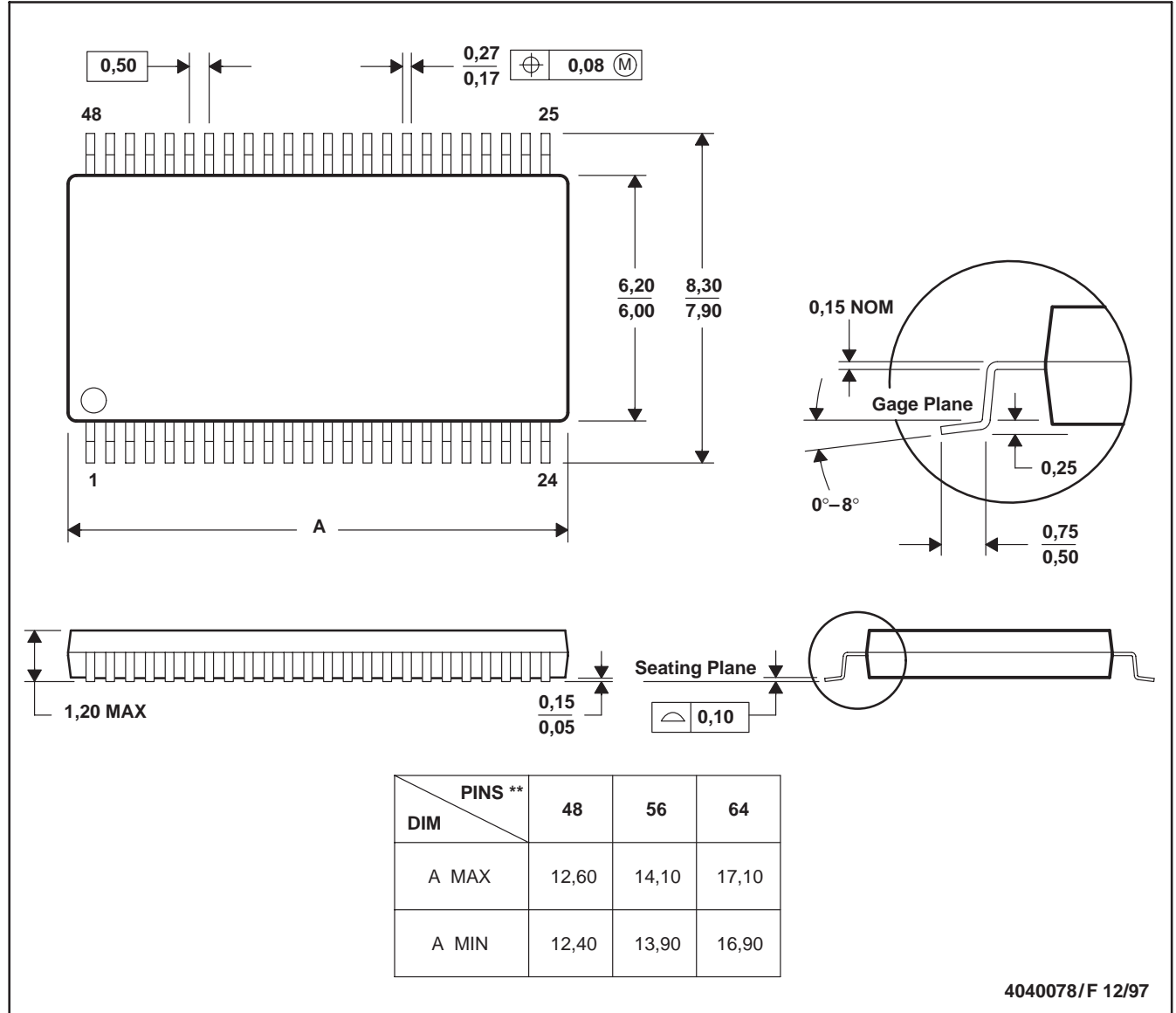
# MECHANICAL DATA

MTSS003D – JANUARY 1995 – REVISED JANUARY 1998

DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold protrusion not to exceed 0,15.
  - D. Falls within JEDEC MO-153

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